

## Materials Declaration

<b>Package</b>	PDIP
<b>Body Size</b>	300 mils
<b>LeadCount</b>	20
<b>Option</b>	PbFree

### Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy Cresol Novolac	16	1.50 E-01	106356
SiO2 Filler	72	6.77 E-01	478601
Phenol Novolac	8	7.52 E-02	53178
Antimony_Sb2O3	2.2	2.07 E-02	14624
Brominated Resin	1.6	1.50 E-02	10636
Carbon Black	0.2	1.88 E-03	1329

### Molding Compound

Item	PPM	Method
Pb	<2	US EPA method #3052 & 6010B
Cd	Not Detected	BS EN 1122:2001 ICP AES
Hg	<2	US EPA method #3052 & 7471A
Cr+6	<2	US EPA method #3060A & 6010B

### Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	4.30 E-01	304089
Fe	2.35	1.04 E-02	7329
P	0.03	1.32 E-04	94
Zn	0.12	5.29 E-04	374

### Die Attach Paste

Item	PPM	Method
Pb	<2	ICP AES
Cd	<2	ICP AES
Hg	<2	ICP AES
Cr+6	<2	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

### Internal Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ag	100	9.21 E-04	652

### External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	2.21 E-02	15600

### Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	2.46 E-04	174

### Chip

Item	% of Chip	Weight (g)	PPM
Si	100	9.08 E-03	6422

### Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	1.92 E-04	136
Ag Filler	75	5.75 E-04	407

### Package Totals

Weight (g)	PPM
1.41 E+00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge  
 ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary

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<b>Option</b>	Sn/Pb

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### Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	4.30 E-01	304089
Fe	2.35	1.04 E-02	7329
P	0.03	1.32 E-04	94
Zn	0.12	5.29 E-04	374

### Die Attach Paste

Item	PPM	Method
Pb	<2	ICP AES
Cd	<2	ICP AES
Hg	<2	ICP AES
Cr+6	<2	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

### Internal Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ag	100	9.21 E-04	652

### External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	1.87 E-02	13260
Pb	15	3.31 E-03	2340

### Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	2.46 E-04	174

### Chip

Item	% of Chip	Weight (g)	PPM
Si	100	9.08 E-03	6422

### Die Attach

Item	% of Die Attach	Weight (g)	PPM
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